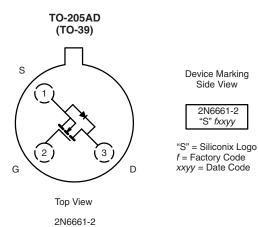


N-Channel 90-V (D-S) MOSFET

PRODUCT SUMMARY					
Part Number	V _{DS} min. (V)	R _{DS(on)} max. (Ω)	V _{GS(th)} (V)	I _D (A)	
2N6661-2	90	4 at V _{GS} = 10 V	0.8 to 2	0.86	



FEATURES

- Low On-Resistance: 3.6 Ω
- Low Threshold: 1.6 V
- Low Input Capacitance: 35 pF
- Fast Switching Speed: 6 ns
- Low Input and Output Leakage

BENEFITS

- Low Offset Voltage
- Low-Voltage Operation
- Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage

APPLICATIONS

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories, Transistors, etc.
- Battery Operated Systems
- Solid-State Relays

Parameter		Symbol	2N6661-2	Unit	
Drain-Source Voltage		V _{DS}	90	V	
Gate-Source Voltage		V _{GS} ± 20		v	
Continuous Drain Current ($T_J = 150 \ ^{\circ}C$)	T _C = 25 °C	la la	0.86		
	T _C = 100 °C	I _D	0.54	A	
Pulsed Drain Current ^a		I _{DM}	± 3		
Power Dissinction	T _C = 25 °C	P _D	6.25	W	
Power Dissipation	T _A = 25 °C	' D	0.725		
Thermal Resistance, Junction-to-Ambient ^b	R _{thJA}	170	°C/W		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 65 to 150	°C	

Notes:

a. Pulse width limited by maximum junction temperature.

b. This parameter not registered with JEDEC.

2N6661-2

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SPECIFICATIONS T _J = 25 °C, unless otherwise noted							
				Lir	nits		
Parameter	Symbol	Test Conditions	Typ. ^a	Min.	Max.	Unit	
Static					_		
Drain-Source Breakdown Voltage	V _{DS}	V_{GS} = 0 V, I_D = 10 μ A	125	90			
	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 1 \text{ mA}$	1.6	0.8	2	v	
Gate-Threshold Voltage		T _A = - 55 °C	1.8		2.5		
		T _A = 125 °C	1.3	0.3			
Coto Rody Lookago	lass	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	~ ^	
Gate-Body Leakage	I _{GSS}	T _A = 125 °C			± 500	nA	
		$V_{DS} = 72 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 72 \text{ V}, V_{GS} = 0 \text{ V}$			100	μA	
		T _A = 125 °C			100		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}$	1.8			А	
		$V_{GS} = 5 \text{ V}, \text{ I}_{D} = 0.3 \text{ A}$	3.8		5.3	Ω	
Drain-Source On-Resistance ^b	R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ A}$	3.6		4		
		$T_A = 125 \ ^{\circ}C^d$	6.7		7.5		
Forward Transconductance ^b	9 _{fs}	$V_{DS} = 7.5 \text{ V}, \text{ I}_{D} = 0.475 \text{ A}$	340	170		mS	
Diode Forward Voltage	V _{SD}	$I_{\rm S} = 0.86$ A, $V_{\rm GS} = 0$ V	0.9	0.7	1.4	V	
Dynamic			•				
Input Capacitance	C _{iss}		35		50		
Output Capacitance	C _{oss}	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$	15		40	рF	
Reverse Transfer Capacitance	C _{rss}	f = 1 MHz	2		10		
Drain-Source Capacitance	C _{ds}		30				
Switching ^c							
Turn-On Time	t _{ON}	V_{DD} = 25 V, _{RL} = 23 Ω	6		10		
Turn-Off Time	t _{OFF}	$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}$ $R_{GS} = 23 \Omega$	8		10	ns	

Notes:

a. For DESIGN AID ONLY, not subject to production testing.

b. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

c. Switching time is essentially independent of operating temperature.

d. This parameter not registered with JEDEC.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



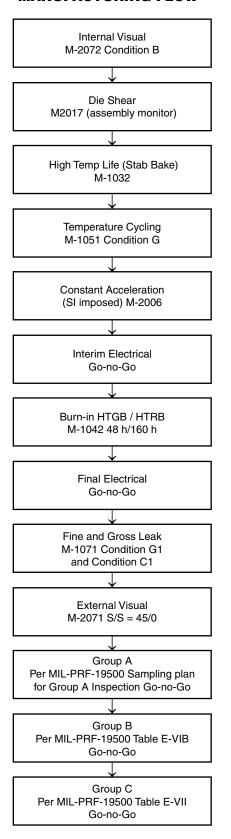
MANUFACTURING FLOW

PROCESS FLOW			
Description	MIL-STD 750 Methods		
Internal Visual	M-2072 Condition B		
Die Shear	M-2017 ^a		
Stabilization Bake	M-1032		
Temperature Cycling	M-1051 Condition G		
Constant Acceleration	M-2006		
Interim Electrical	Go-no-Go		
Burn-In (HTGB)	M1042_Condition B (48 h)		
Burn-In (HTRB)	M1042_Condition A (160 h)		
Final Electrical	Go-no-Go		
Fine Leak	M-1071 Condition G1		
Gross Leak	M-1071 Condition C1		
External Visual	M-2071 S/S = 45/0		
Group A Per MIL-PRF-19500 Sampling plan for Group A Inspection	per spec.		
Group B Per MIL-PRF-19500	per spec.		
Group C Per MIL-PRF-19500	per spec.		
Deltas Option	per spec. ^b		
Solder Dip Option	per spec. ^b		

Notes:

a. Test performed on line during assembly procedure (monitor).

b. Per spec is a reference to Vishay Siliconix data sheet or customer SCD whichever applies.

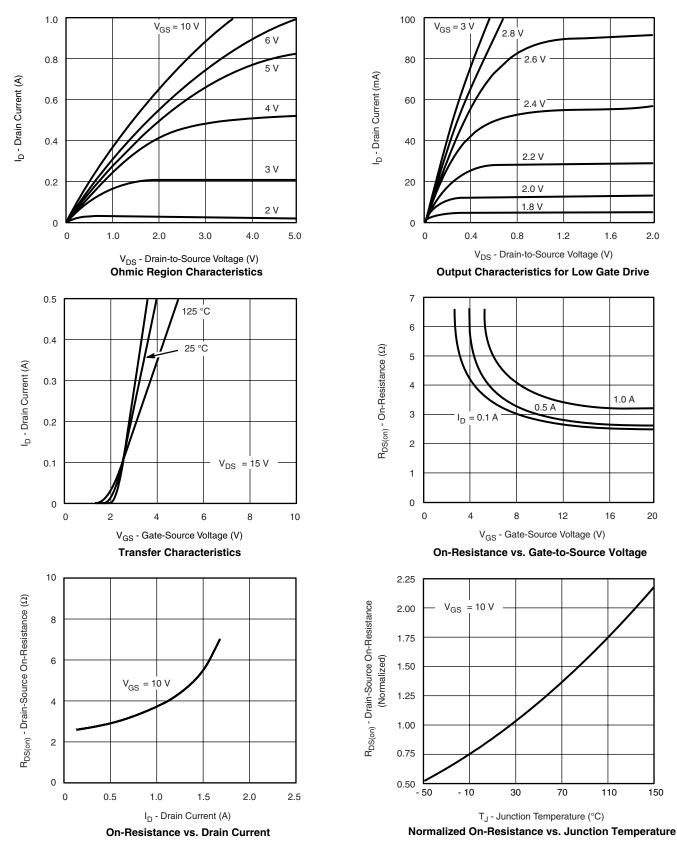


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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



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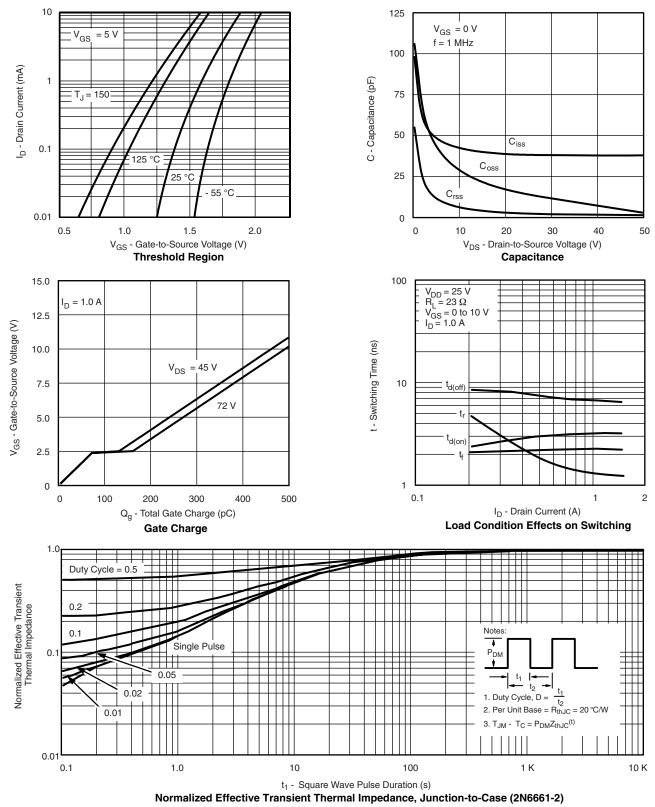




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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see http://www.vishay.com/ppg?68632.

Document Number: 68632 S-81302-Rev. A, 09-Jun-08



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